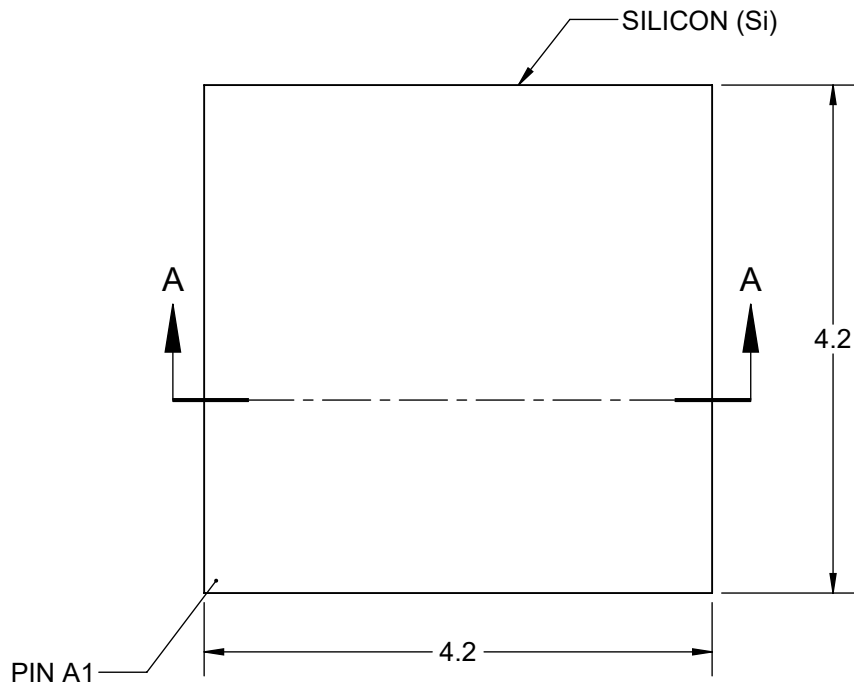
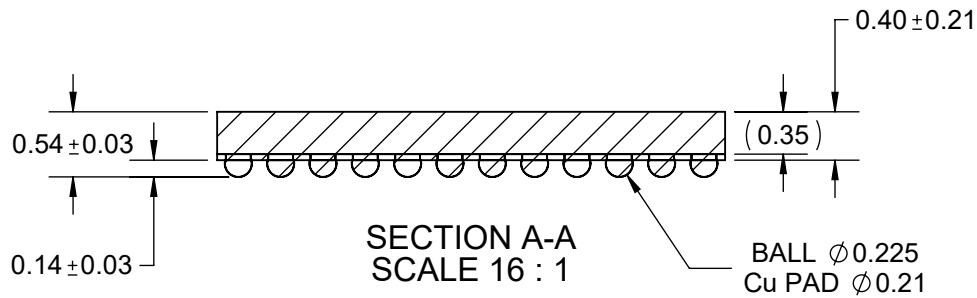
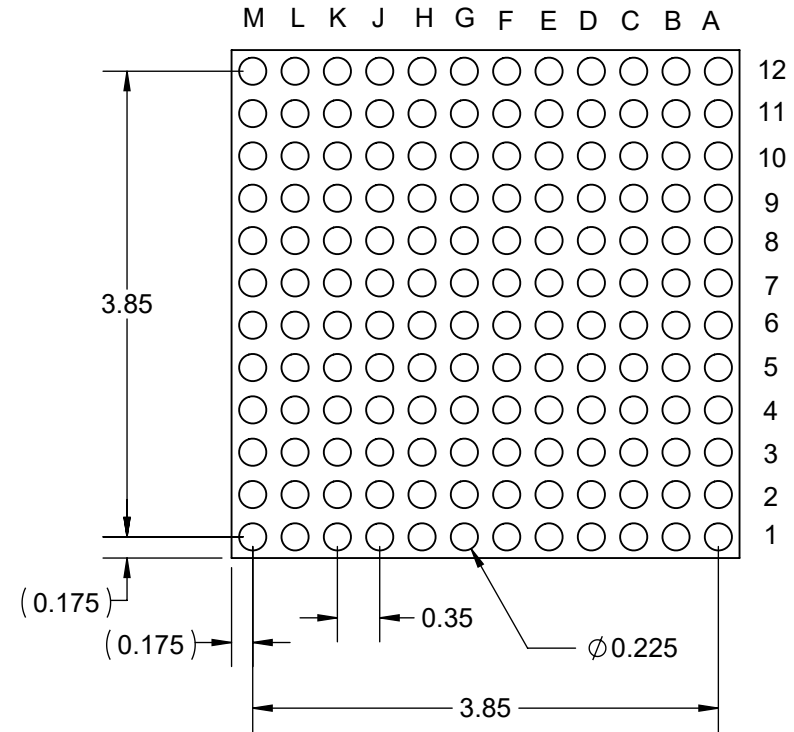


### TOP VIEW



### BALL VIEW



Notes: (Unless Otherwise Specified).

- 1) DIMENSIONS: mm
- 2) SOLDER BALL ALLOY: SAC305 (Sn96.5/Ag3.0/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW)  $\phi 0.225\text{mm} \pm 0.03$ .
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER:  $\phi 0.21\text{mm}$ .
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) ISOLATED PAD PATTERN (SEE PAGE 2).

SECTION A-A  
SCALE 16 : 1

BALL  $\phi 0.225$   
Cu PAD  $\phi 0.21$

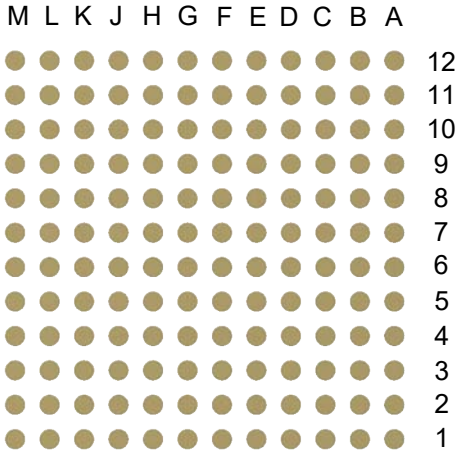
#### PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP144T.35C-ISO-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

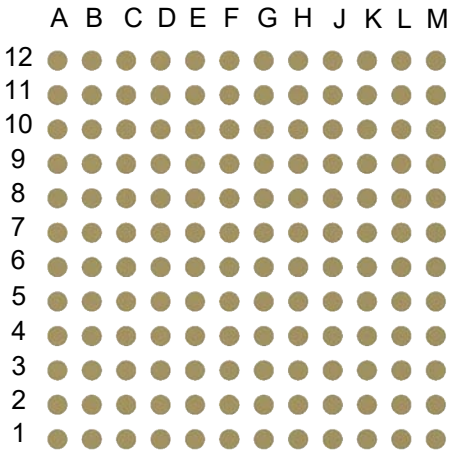
APPROVALS	DATE	<b>TopLine</b> <sup>®</sup>			
DRAWN T. Au	7/2/2023				
ENG M. Hart	7/2/2023	TITLE		WLP144T.35C-ISO-D 144 BALL P=0.35mm	
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		40:1	A	571277	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 5
REVISED					

**ISOLATED PAD PATTERN**

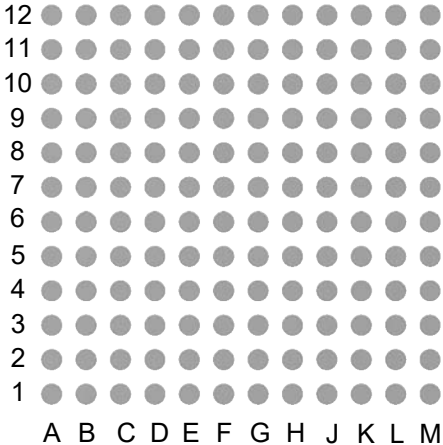
**BALL VIEW**



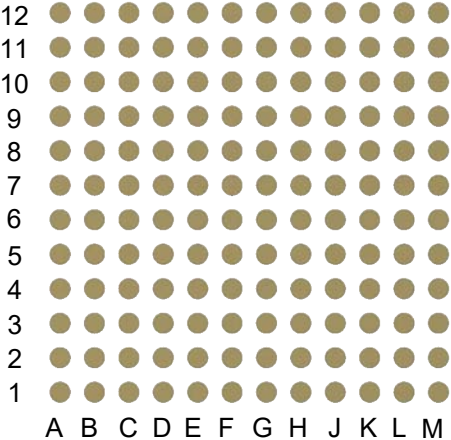
**BOTTOM SIDE  
(TOP X-RAY VIEW)**



**PC BOARD**



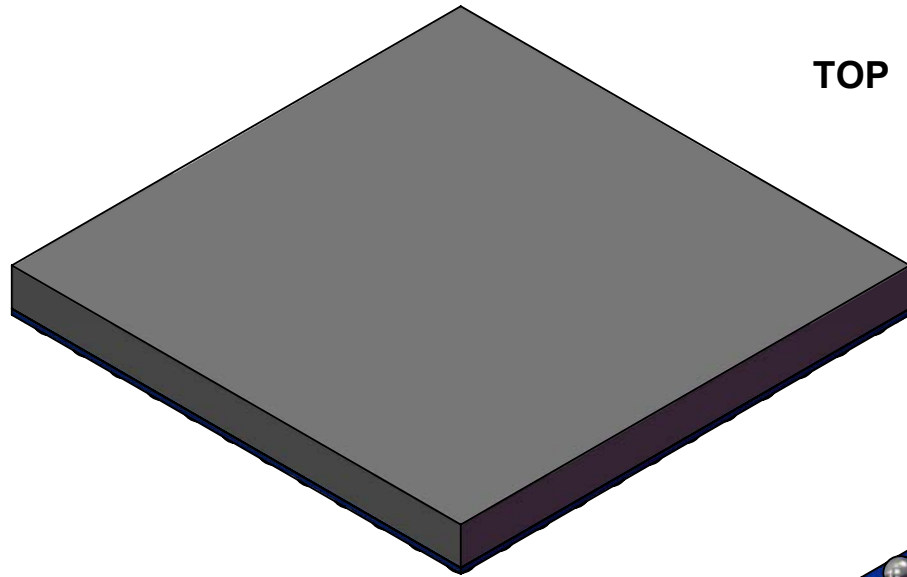
**AFTER MOUNTING  
TO TEST BOARD  
(TOP X-RAY VIEW)**



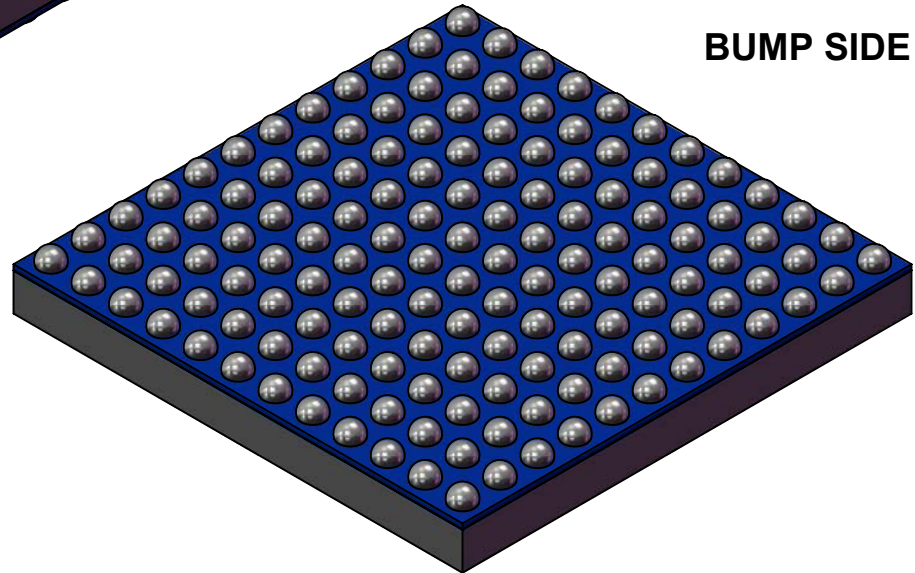
- Notes:
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
  - 2) PCB Cu BALL PAD DIAMETER:  $\varnothing 0.21\text{mm}$  (8.2 mil).
  - 3) PCB PAD TRACING LINE WIDTH 0.10mm (4 mil).

<b>TopLine<sup>®</sup></b>			
TITLE		WLP144T.35C-ISO-D 144 BALL P=0.35mm	
SCALE	SIZE	DRAWING NO.	REV
25:1	A	571277	A
DO NOT SCALE DRAWING			SHEET 2 OF 5

**MODEL**



**TOP**



**BUMP SIDE**

**TopLine<sup>®</sup>**

TITLE WLP144T.35C-ISO-D  
144 BALL P=0.35mm

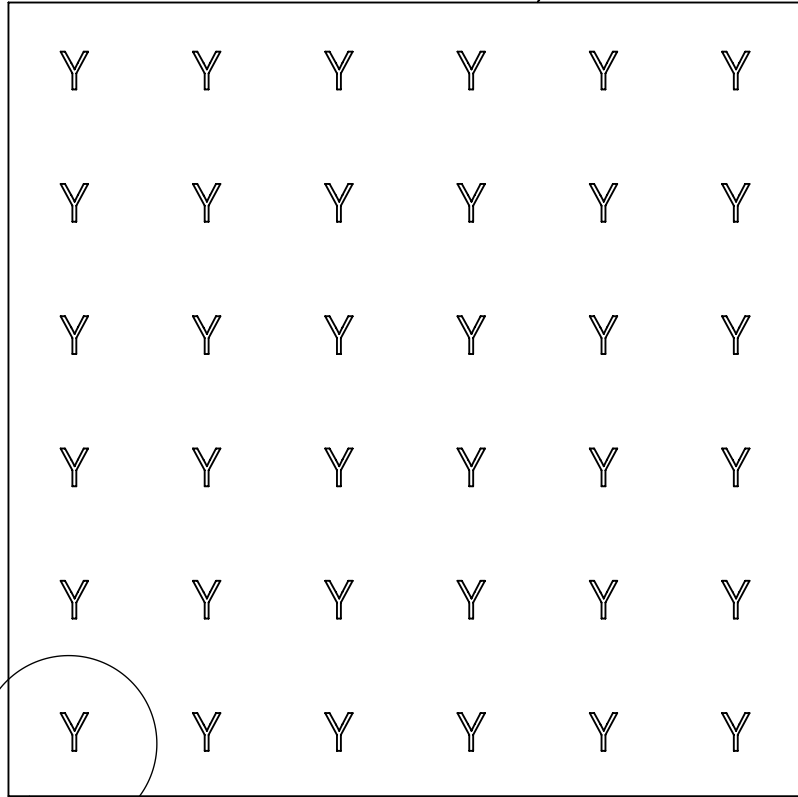
SCALE 40:1	SIZE A	DRAWING NO. 571277	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 5

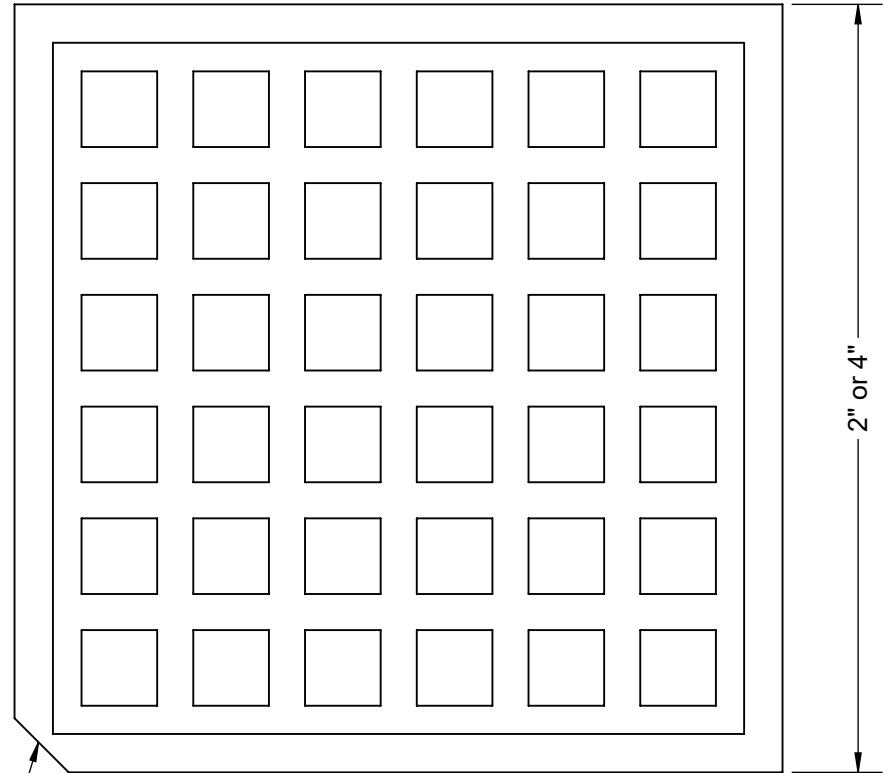
**TOP VIEW**

SILICON (Si)



EXAMPLE ORIENTATION OF MARKING ON WLP

**TYPICAL WAFFLE PACK IC CHIP TRAY SCALE = 2:1**



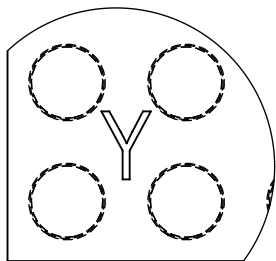
NUMBER OF POCKETS WILL CHANGE BASED ON THE SIZE OF THE WLP CHIP

B

PIN 1

PIN 1 CHAMFER

2" or 4"



ISOLATED PAD ORIENTATION  
DETAIL B  
SCALE 45 : 1

Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (BALL) SIDE.

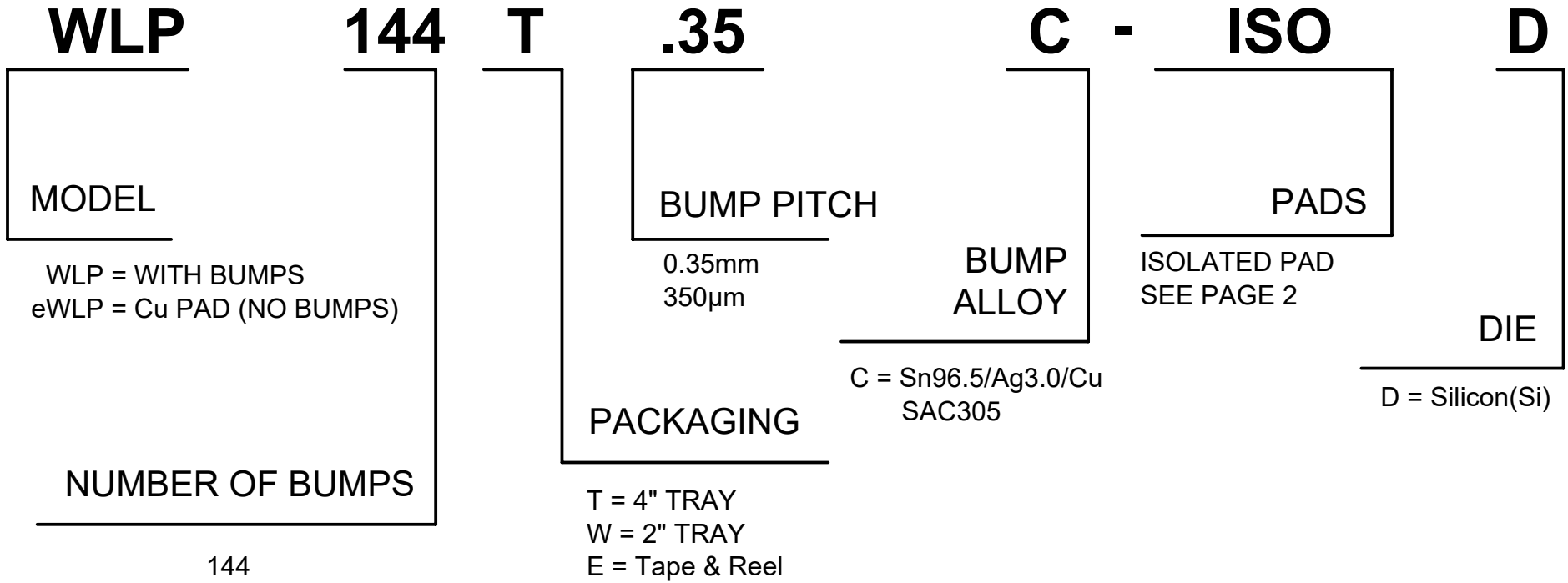
MARKING CODE	
PITCH	LETTER
0.35mm	Y

\* SUBJECT TO CHANGE

**TopLine<sup>®</sup>**

TITLE		WLP144T.35C-ISO-D 144 BALL P=0.35mm	
SCALE	SIZE	DRAWING NO.	REV
30:1	A	571277	A
DO NOT SCALE DRAWING		SHEET 4 OF 5	

## PART NUMBER SYSTEM



PART NUMBER	PACKAGING	QTY
WLP144W.35C-ISO-D	2" CHIP TRAY	49
WLP144T.35C-ISO-D	4" CHIP TRAY	196
WLP144E.35C-ISO-D	T&R	1000

<b>TopLine<sup>®</sup></b>			
TITLE		WLP144T.35C-ISO-D 144 BALL P=0.35mm	
SCALE	SIZE	DRAWING NO.	REV
30:1	A	571277	A
DO NOT SCALE DRAWING			SHEET 5 OF 5